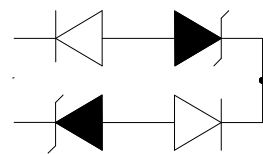




350 watts peak pulse power per line ($t_P=8/20\mu s$)
Protects one bi-directional I/O line
Low clamping voltage
Working voltage:3.3V
Low leakage current
RoHS compliant

Cell phone handsets and accessories
Microprocessor based equipment
Personal digital assistants (PDA's)
Notebooks, desktops, and servers
Portable instrumentation
Peripherals
USB interface

SOD-323



IEC61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
IEC61000-4-4 (EFT) 40A (5/50ns)
IEC61000-4-5 (Lightning) 20A (8/20 μs)

SOD-323 package
Molding compound flammability rating: UL 94V-0
Quantity per reel: 3,000pcs
Lead finish: lead free
Marking code: CA1

(T_A=25 , RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation at 8/20μs waveform	P _{PP}	350	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	+/- 30 +/- 30	kV
Lead soldering temperature	T _L	260 (10 sec.)	
Operating junction temperature range	T _J	-55 to +125	
Storage temperature range	T _{STG}	-55 to +150	

FIG.3: Pulse derating curve

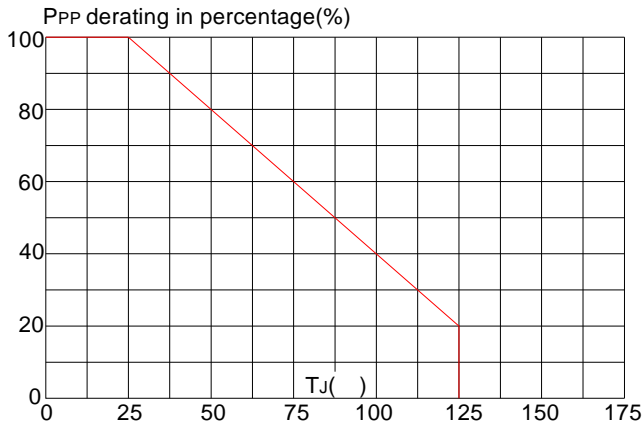
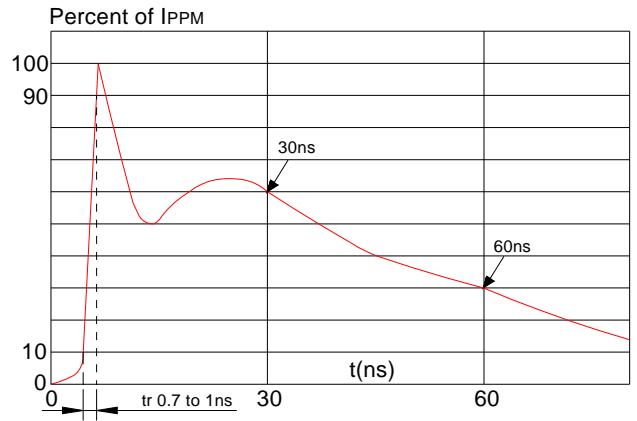
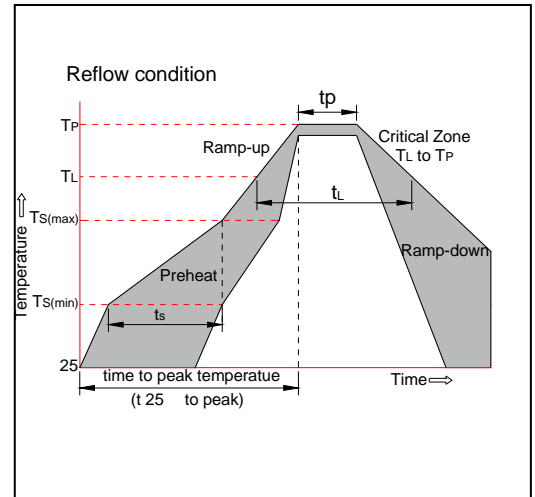
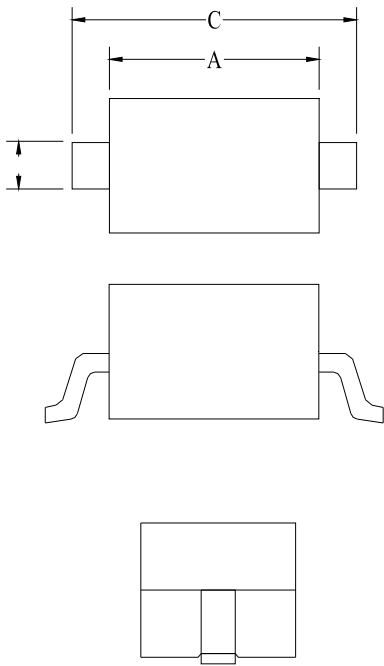


FIG.4: ESD clamping (30kV contact)



Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min (T _{s(min)})	+150
	-Temperature Max(T _{s(max)})	+200
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T _L)to peak)		3 /sec. Max
T _{s(max)} to T _L - Ramp-up Rate		3 /sec. Max
Reflow	-Temperature(T _L)(Liquidus)	+217
	-Temperature(t _L)	60-150 secs.
Peak Temp (T _p)		+260(+0/-5)
Time within 5 of actual Peak Temp (t _p)		20-40secs.
Ramp-down Rate		6 /sec. Max
Time 25 to Peak Temp (T _p)		8 min. Max
Do not exceed		+260





TVS Diode Array

